Nanopatterned Silicon Stamps

PRODUCT OVERVIEW

II-VI Nanopatterned Silicon Stamps consist of nanoscale-textured surfaces patterned on single-crystal silicon substrates. Through reactive ion etching, linear grooves with a trapezoidal cross-section are etched into the substrate surface, resembling conventional gratings. The etching process enables different period and depth specifications for these grooves, as well as more complex patterns such as lattices. II-VI Nanopatterned Silicon Stamps are ideal for nanophotonics research applications in the fields of optics and photonics, biology, chemistry, nanoimprinting, and microfluidics.

 Product Key
 SNS - C11.7 - 1212 - 200 - P

 Silicon nano stamp
 Groove depth

 Bilicon nano stamp
 Bilicon nano stamp

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 Rev. 01

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Specifications

Part Number	Period	Groove Depth	Line width	Width x Height	Clear aperture	Thickness
SNS-C11.7-1212-200-P	855 nm	200 nm	425 nm	12.5 x 12.5 mm	11.5 x 11.5 mm	0.675 mm
SNS-C11.7-2525-200-P	855 nm	200 nm	425 nm	25.0 x 25.0 mm	24.0 x 24.0 mm	0.675 mm
SNS-C72-1212-50-P	139 nm	50 nm	50 nm	12.5 x 12.5 mm	11.5 x 11.5 mm	0.830 mm
SNS-C72-2525-50-P	139 nm	50 nm	50 nm	25.0 x 25.0 mm	24.0 x 24.0 mm	0.830 mm

Tolerances 0.001 lines/mm $\pm 10\%$ $\pm 10\%$ $\pm 0.2 \text{ mm}$ N/Δ ± 0.0		Period *	Groove Depth	Line width	Width x Height	Clear aperture	Thickness
	Tolerances	0.001 lines/mm	±10%	±10%	± 0.2 mm	N/A	± 0.05 mm

* variation over 10 mm

Substrate material: Single crystal silicon

Front side:

Back side:

DUV lithographic patterning and Reactive Ion Etch into the substrate. fine grind (not polished)

Sidewall angle: 87° typical

Surface quality in clear aperture: 60/40 Scratch/Dig per MIL-PRF-13830B



